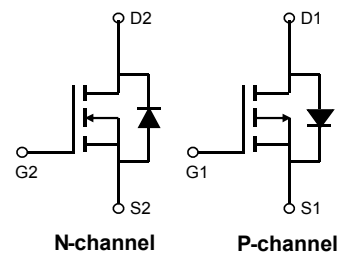
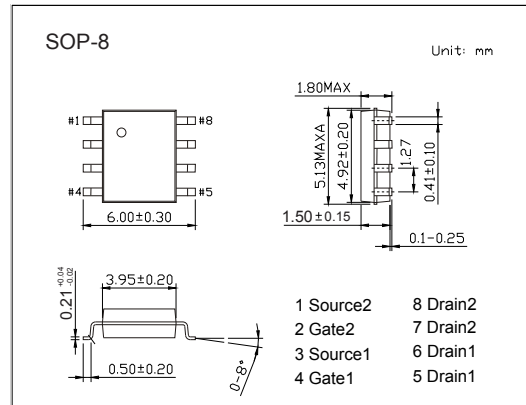


Complementary Trench MOSFET

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■ Features

- N-Channel: $V_{DS}=40V$ $I_D=8.5A$
 $R_{DS(ON)} < 28m\Omega$ ($V_{GS}=10V$)
 $R_{DS(ON)} < 37m\Omega$ ($V_{GS}=4.5V$)
- P-Channel: $V_{DS}=-40V$ $I_D=-7.5A$
 $R_{DS(ON)} < 53m\Omega$ ($V_{GS}=-10V$)
 $R_{DS(ON)} < 81m\Omega$ ($V_{GS}=-4.5V$)
- Green Device: RoHS compliant.
- Ultra-Low Gate Charge: Reduces switching losses for high efficiency.
- Superior CdV/dt Immunity: Minimizes noise and false triggering.
- High Cell Density Trench Technology: Optimizes on-resistance and current handling.



■ Application

- Synchronous Buck Converters
- DC-DC Power Supplies
- High-Efficiency Switching Circuits
- Consumer Electronics (e.g., laptops, adapters)
- Industrial Automation Systems

■ Absolute Maximum Ratings($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter		Max. N-channel	Max. P-channel	Units
V _{DSS}	Drain-Source Voltage		40	-40	V
V _{GSS}	Gate-Source Voltage		±20	±20	V
I _D	Continuous Drain Current	T _A = 25°C	8.5	-7.5	A
		T _A = 100°C	5.2	-3.9	A
I _{DM}	Pulsed Drain Current ^{note1}		32	-24	A
P _D	Power Dissipation	T _A = 25°C	2	3.2	W
R _{θJA}	Thermal Resistance, Junction to Ambient		62.5	39	°C/W
E _{AS}	Single Pulse Avalanche Energy		13	17.6	mJ
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C

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■ N-ch MOSFET Electrical Characteristics(T_J=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.8	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =8A	-	22	28	mΩ
		V _{GS} =4.5V, I _D =5A	-	29	37	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1.0MHz	-	633	-	pF
C _{oss}	Output Capacitance		-	67	-	pF
C _{rss}	Reverse Transfer Capacitance		-	58	-	pF
Q _g	Total Gate Charge	V _{DS} =20V, I _D =8A, V _{GS} =10V	-	12	-	nC
Q _{gs}	Gate-Source Charge		-	3.2	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	3.1	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = 20V, R _L =2.5Ω V _{GS} =10V,R _{REN} =3Ω	-	4	-	ns
t _r	Turn-on Rise Time		-	3	-	ns
t _{d(off)}	Turn-off Delay Time		-	15	-	ns
t _f	Turn-off Fall Time		-	2	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	8.5	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	32	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = 8A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25°C, V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25Ω, I_{AS}=7.2A

T_J=25°C, V_{DD}=-20V, V_G= -10V, L=0.5mH, R_g=25Ω, I_{AS}=-8.4A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Complementary Trench MOSFET

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■ P-ch MOSFET Electrical Characteristics(TJ=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} =0V	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-1.0	-1.6	-2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} = -10V, I _D = -6A	-	39	53	mΩ
		V _{GS} = -4.5V, I _D = -4A	-	58	81	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -20V, V _{GS} =0V, f=1.0MHz	-	860	-	pF
C _{oss}	Output Capacitance		-	87	-	pF
C _{rss}	Reverse Transfer Capacitance		-	70	-	pF
Q _g	Total Gate Charge	V _{DS} = -20V, I _D = -6A, V _{GS} = -10V	-	13	-	nC
Q _{gs}	Gate-Source Charge		-	3.8	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	3.1	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -20V, R _L =2.3Ω V _{GS} =-10V,R _{REN} =6Ω	-	7.5	-	ns
t _r	Turn-on Rise Time		-	5.5	-	ns
t _{d(off)}	Turn-off Delay Time		-	19	-	ns
t _f	Turn-off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7.5	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-24	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -6A	-	-	-1.2	V

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■ Typical Performance Characteristics-N

Figure 1: Output Characteristics

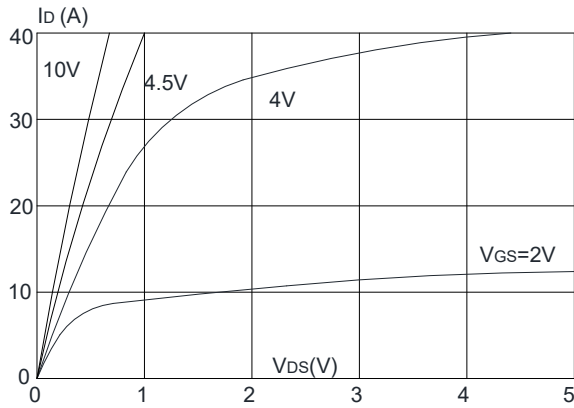


Figure 2: Typical Transfer Characteristics

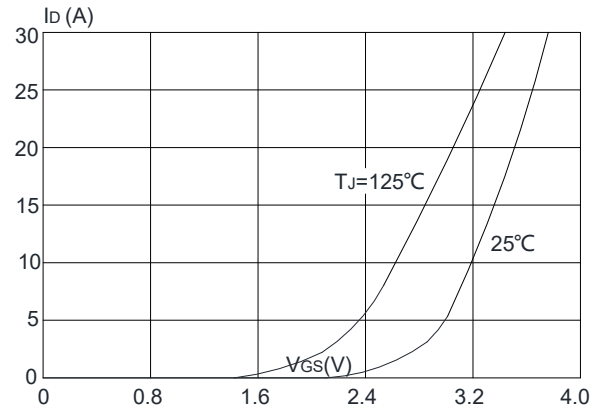


Figure 3: On-resistance vs. Drain Current

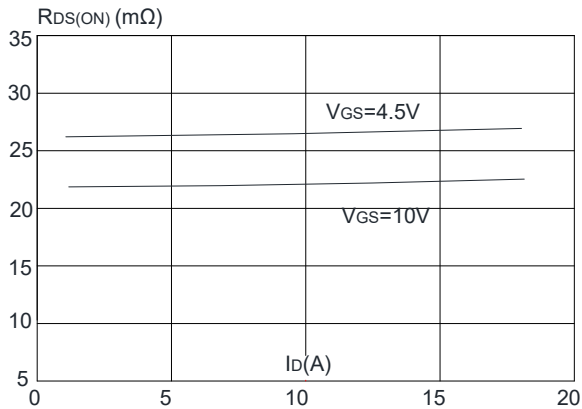


Figure 4: Body Diode Characteristics

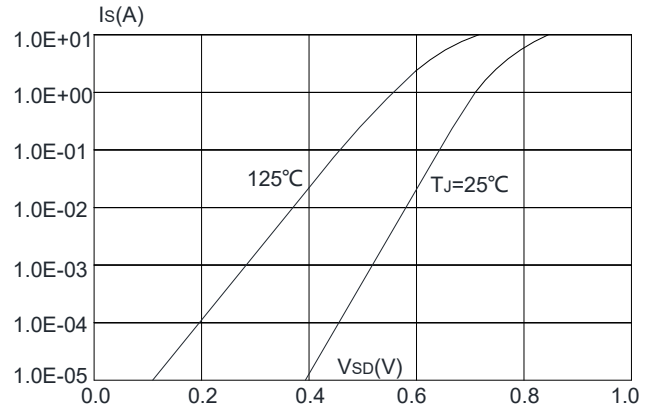


Figure 5: Gate Charge Characteristics

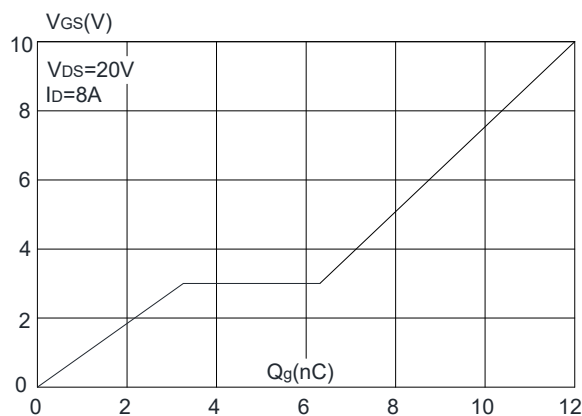
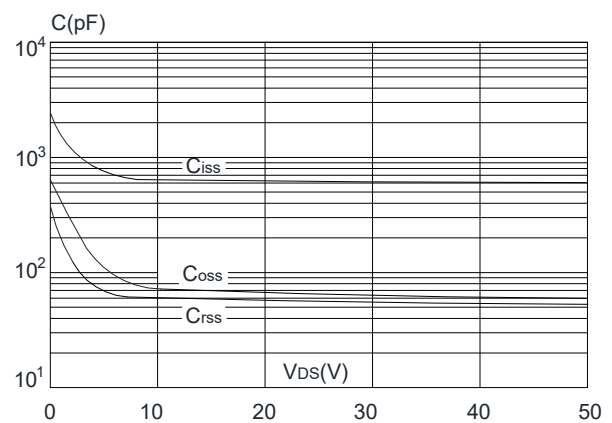


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

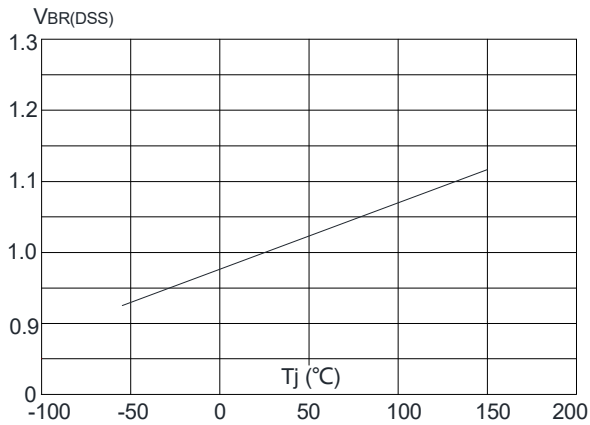


Figure 8: Normalized on Resistance vs. Junction Temperature

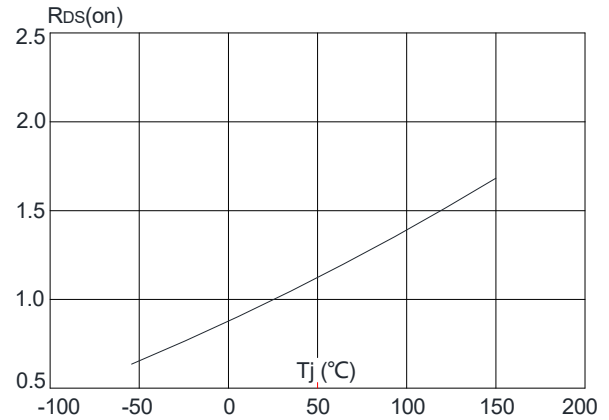


Figure 9: Maximum Safe Operating Area

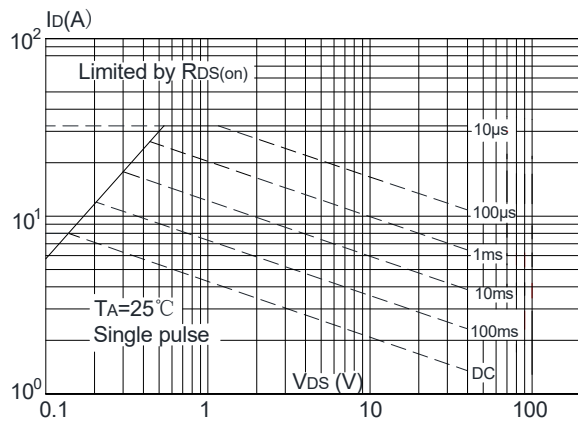


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

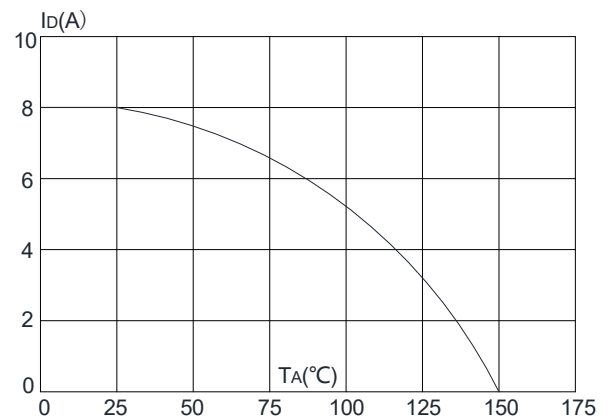
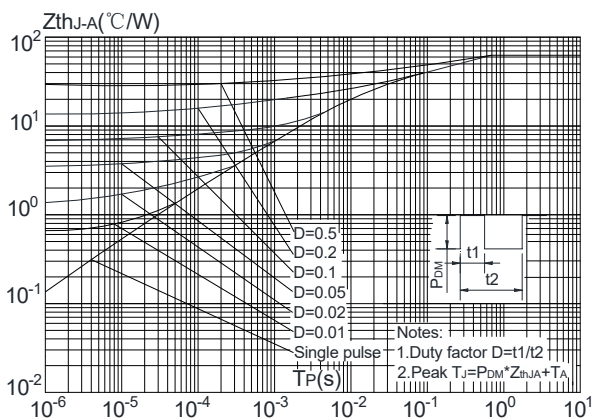


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



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■ Typical Performance Characteristics-P

Figure1: Output Characteristics

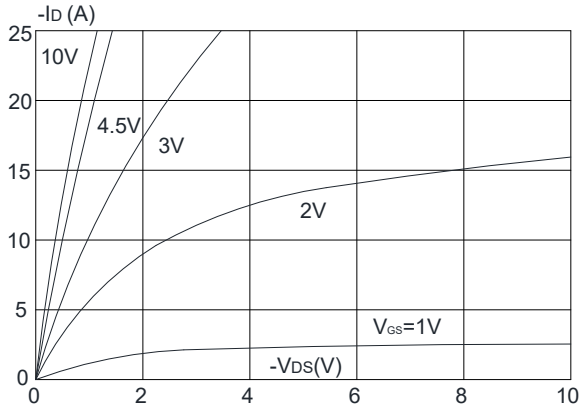


Figure 2: Typical Transfer Characteristics

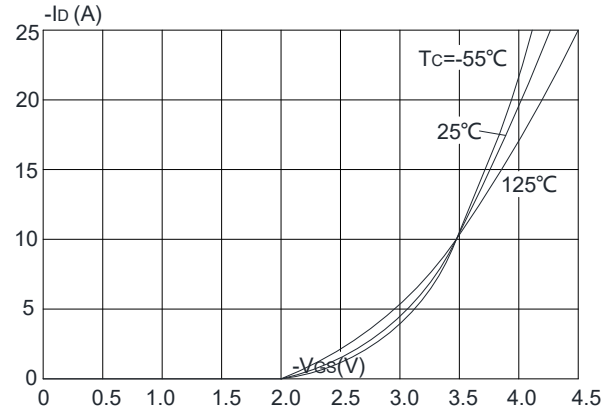


Figure 3: On-resistance vs. Drain Current

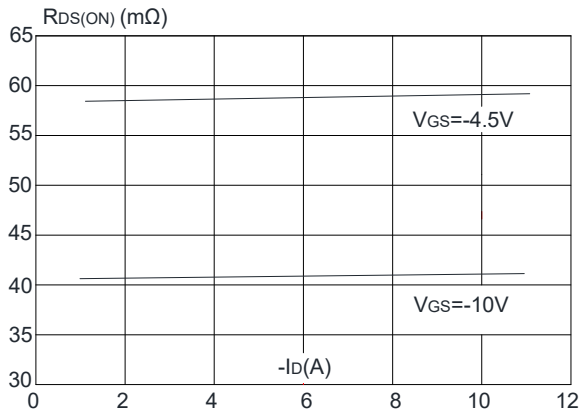


Figure 4: Body Diode Characteristics

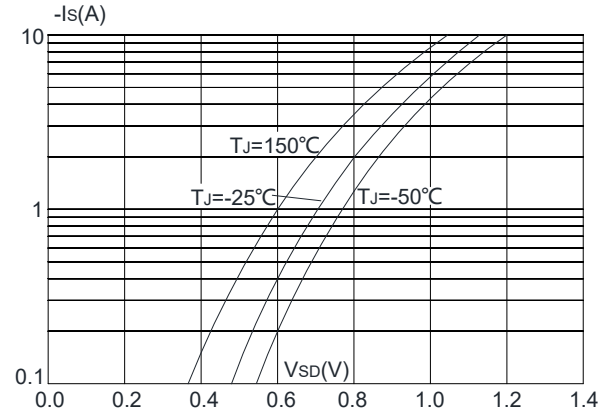


Figure 5: Gate Charge Characteristics

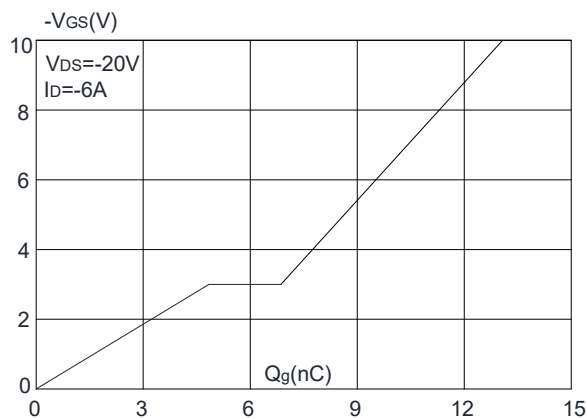
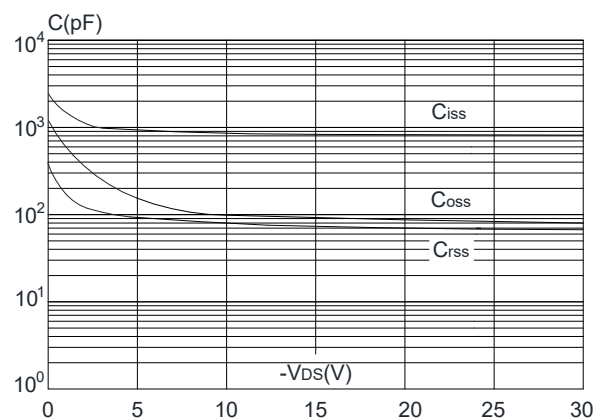


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

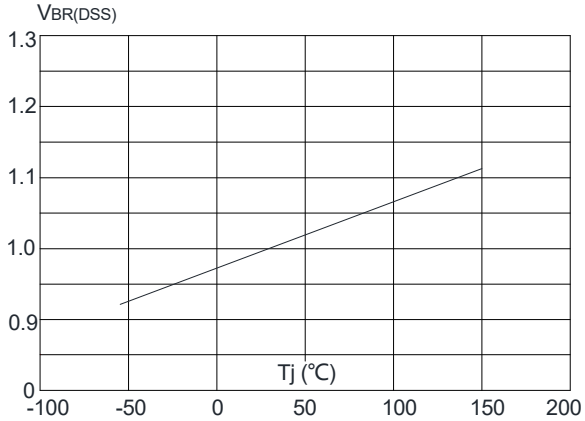


Figure 8: Normalized on Resistance vs. Junction Temperature

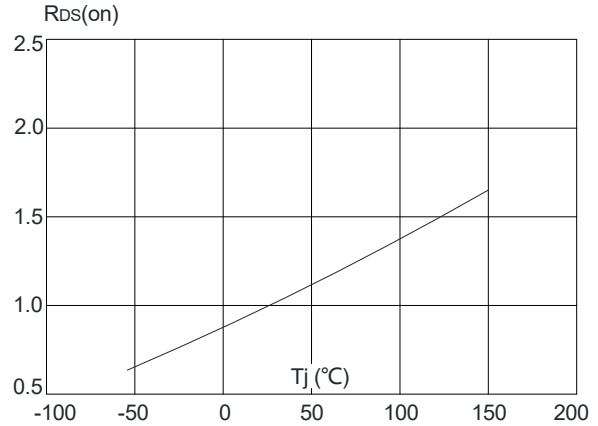


Figure 9: Maximum Safe Operating Area

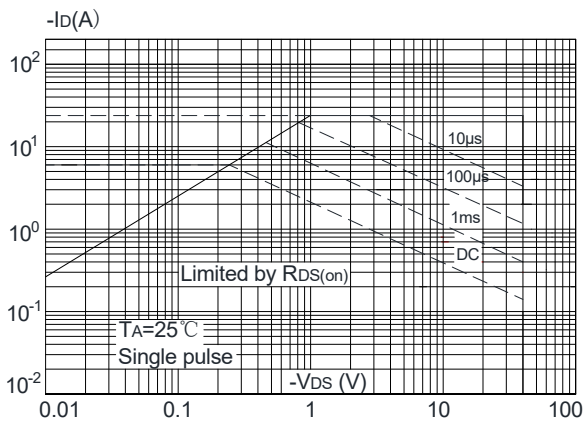


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

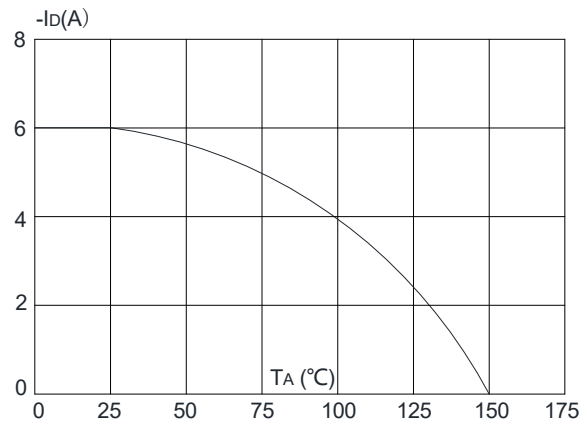


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

